



Initial Product/Process Change Notification

Document #: IPCN25284X

Issue Date: 21 Mar 2023

Title of Change:	NCP308MTADJTBG Fab Capacity Addition at onsemi Aizu Japan							
Proposed First Ship date:	30 Jul 2023 or earlier if approved by customer							
Contact Information:	Contact your local onsemi Sales Office or Mat.Hilton@onsemi.com							
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.							
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >							
Marking of Parts/ Traceability of Change:	There is no change to the die marking. Traceability will be maintained by the manufacturing lot number.							
Change Category:	Wafer Fab Change							
Change Sub-Category(s):	Manufacturing Site Addition							
Sites Affected:								
onsemi Sites	External Foundry/Subcon Sites							
onsemi Aizu, Japan	None							
Description and Purpose:								
<p>This initial notification announces the intention to qualify the onsemi Aizu Japan fab for the NCP308MTADJTBG part number. The NCP308MTADJTBG is currently fabricated in the onsemi Gresham Oregon FAB. Upon approval of the FPCN, the NCP308MTADJTBG may be fabricated in either onsemi Gresham Oregon or onsemi Aizu Japan as shown in the table below.</p> <table border="1"> <thead> <tr> <th></th> <th>From</th> <th>To</th> </tr> </thead> <tbody> <tr> <td>Fab Site</td> <td>onsemi, Gresham Oregon, USA</td> <td>onsemi, Gresham Oregon, USA or onsemi Aizu, Japan</td> </tr> </tbody> </table>				From	To	Fab Site	onsemi, Gresham Oregon, USA	onsemi, Gresham Oregon, USA or onsemi Aizu, Japan
	From	To						
Fab Site	onsemi, Gresham Oregon, USA	onsemi, Gresham Oregon, USA or onsemi Aizu, Japan						
<p>Aizu die will have a narrower scribe width.</p> <p>There are no product material changes as a result of this change.</p> <p>There is no product marking change as a result of this change.</p>								



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Qualification Plan:

QV DEVICE NAME: NCP308MTADJTBG

RMS: S87946

PACKAGE: WDFN6 2*2

Test	Specification	Condition	Interval
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

Estimated date for qualification completion: 14 April 2023

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
NCP308MTADJTBG	NCP308MTADJTBG